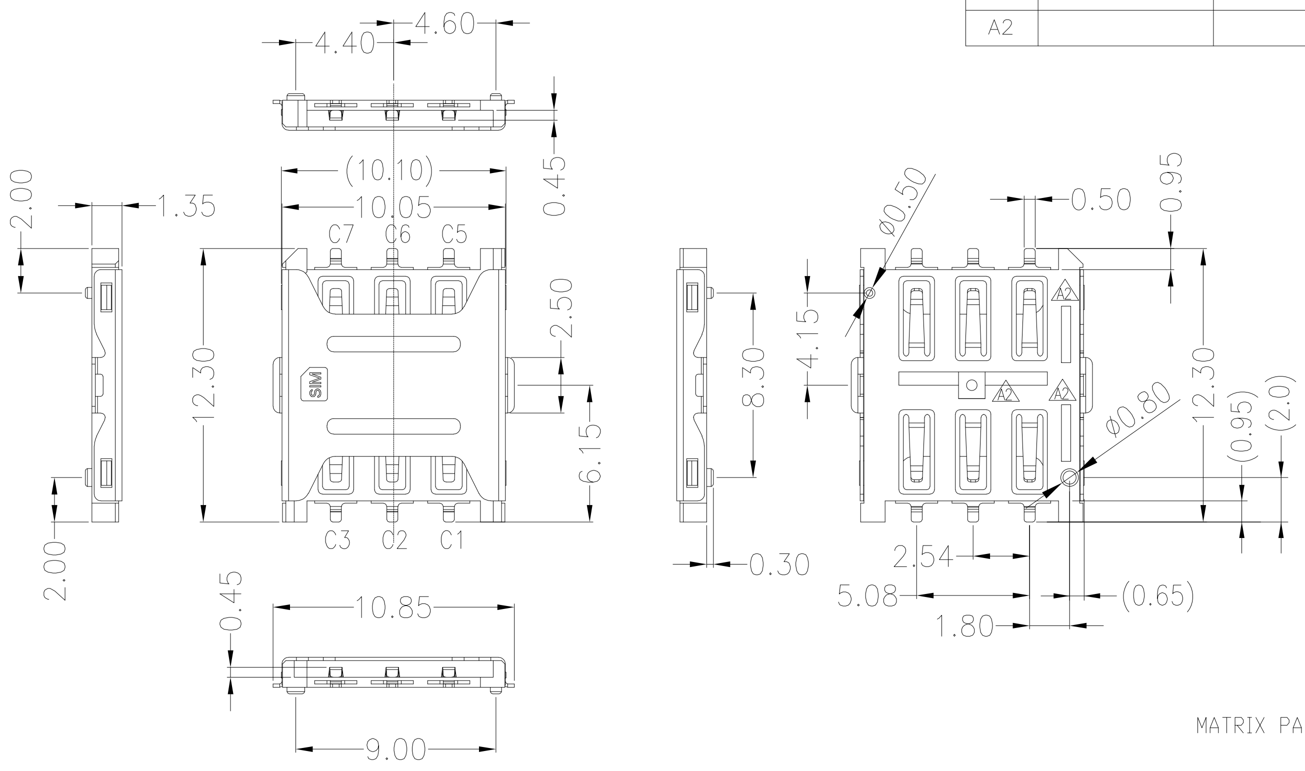
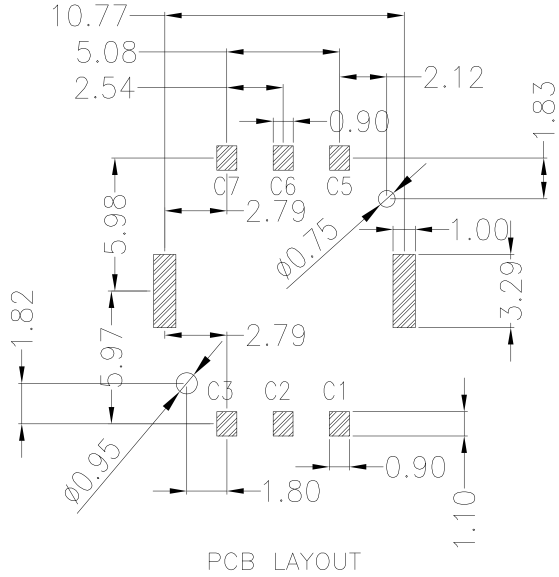
GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2015/08/09	Phebe Su
A1			Update Note	2018/11/09	Phebe Su
A2			增加塑料注塑口	2020/12/16	Hanson



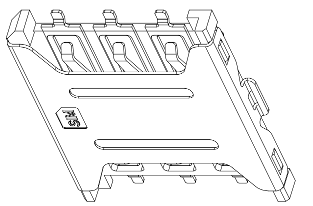


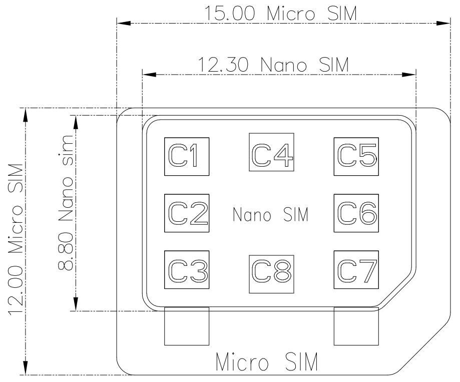
PCB LAYOUT

MATRIX PART NO:

MSM – 02 – 01 – 06 – 13 – 21

- MSM: Matrix SIM
- 02: 01: Push / 02: Non-Push
- 01: Plating 01:G/F 30:30u
- 06: Pin number 06:6pin 08:8pin
- 13: Height
- 21: Series Number





Note:

MATERIAL:

Insulator: LCP UL94V-0,BLACK

Contact: C5210

SHELL: SUS304

PLATING:

Contact: G/F OVER Ni.

Shell: G/F PLATED ON SOLDER AREA, Ni PLATED OVERALL

Electrical:

Current Rating: 0.5A

Voltage Rating: 125V AC/DC

Ambient Temperature Range: -40°C~+85°C

Storage Temperature Range: -40°C~+85°C

Ambient Humidity Range: 95% R.H. Max.

Contact Resistance:100mΩ max.

Insulation Resistance:1000MΩ min./500VDC

Mating Cycles:5,000 Insertions

Reflow peak temp.:260°C ±5°C, 3~5 S

SIM pin assignment

PIN#	Name
C1	VCC供电电压
C2	RST重置
C3	CLK时钟
C5	GND接地
C6	VPP程序电压
C7	I/O输入输出

Matrix Electronics Co.,Ltd

TOLERANCE: X. X.X ±0.35 X.XX ±0.25 X.XXX ±0.15 ANGLE: ±3°	DESIGN BY : Hanson Huang	DATE : 2020/12/16	PART NAME: Nano SIM 1.35H
	CHECKED BY: Vicky Hsieh	DATE : 2020/12/16	PART NO. MSM-02-01-06-13-21
UNIT: mm [inch]	APPROVED BY1: Richard Hsieh	DATE : 2020/12/16	MOLD NO. NA
SCALE:1:1 SIZE:A4	APPROVED BY2: Richard Hsieh	DATE : 2020/12/16	DRAW NO. SHEET NO. 1 OF 1